

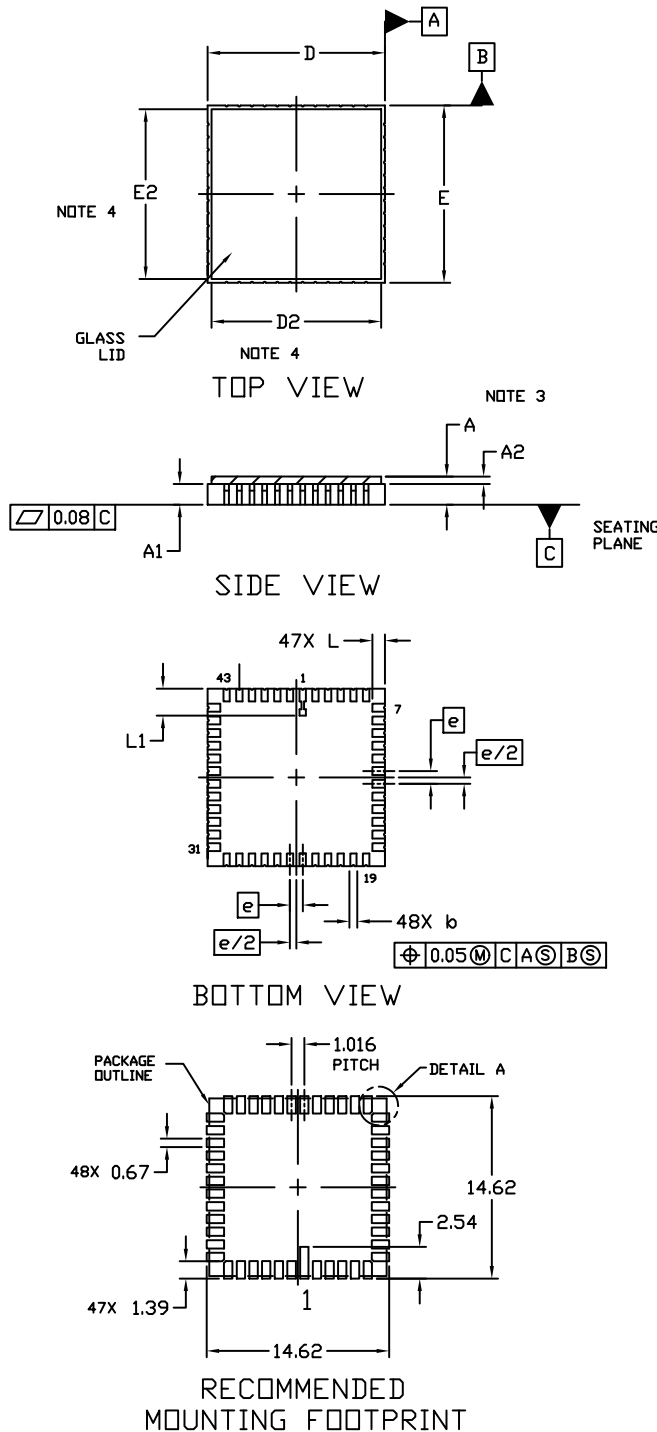
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



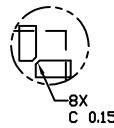
LCC48, 14.22x14.22 CASE 115AO ISSUE A

DATE 31 JAN 2012



NOTES:

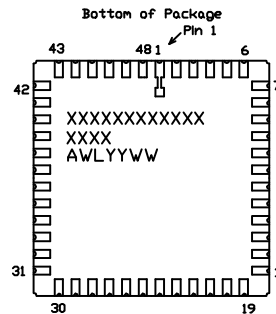
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. THE LID DEFINED BY DIMENSIONS D2 AND E2 MUST BE LOCATED WITHIN DIMENSIONS D AND E.



DETAIL A

DIM	MILLIMETERS	
	MIN.	MAX.
A	1.85	2.55
A1	1.65 REF	
A2	0.55 REF	
b	0.43	0.59
D	14.09	14.35
D2	13.60 REF	
E	14.09	14.35
E2	13.60 REF	
e	1.016 BSC	
L	0.84	1.20
L1	1.90	2.42

GENERIC MARKING DIAGRAM



- XXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- NNNN = Serial Number

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DESCRIPTION:	LCC48, 14.22 X 14.22	PAGE 1 OF 1

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